

Title (en)  
METAL NANO-OBJECTS, FORMED ON SEMICONDUCTOR SURFACES, AND METHODS FOR MAKING SAID NANO-OBJECTS

Title (de)  
AUF OBERFLÄCHE VON HALBLEITERN HERGESTELLTE METALLISCHE NANO-OBJEKTE, UND DEREN HERSTELLUNGSVERFAHREN

Title (fr)  
NANO-OBJETS METALLIQUES, FORMES SUR DES SURFACES DE SEMICONDUCTEURS, ET PROCEDE DE FABRICATION DE CES NANO-OBJETS

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Application  
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Abstract (en)  
[origin: WO2004005593A2] The invention concerns metal nano-objects, formed on semiconductor surfaces, and a method for making said nano-objects. The invention is applicable in nanoelectronics for example to obtain nano-objects (4) by deposition of a metal on a prepared cubic SiC surface (2).

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